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## **Metryx Launches 300mm Mass Metrology Tool for High Volume Semiconductor Manufacturing**

**BRISTOL, UK – January 10, 2006** – Designed for monitoring critical semiconductor device manufacturing process steps on product wafers in a variety of applications, including memory, logic and power components, metrology specialists Metryx today introduced the Mentor DF3, a mass metrology tool offering atomic layer measurement accuracy for high volume 300 mm manufacturing environments.

The DF3 is designed to monitor changes in process performance and quickly determine whether device manufacturers process steps are operating correctly by measuring the mass of any wafer following a process step. Simple comparison with the measurements of a reference wafer enable the tool to reliably and accurately identify process changes after deposition, wet or dry etch, or CMP Processing. The tool achieves measurements down to resolutions as low as 10 microgram (the equivalent of one Angstrom of material thickness).

“The DF3 builds on the technology first brought into production with the Mentor SF3, but makes this critical mass measurement technology available for high volume 300mm manufacturing environments,” explained Dr. Adrian Kiermasz, president and CEO for Metryx. “Metryx has now successfully completed a number of installations in this market and the rapid acceptance of the technology clearly demonstrates that mass metrology solves problems that no other metrology equipment has yet been able to achieve.”

Capable of throughputs in excess of 60 wafers per hour, the Mentor DF3 tool has a small footprint of only 2m<sup>2</sup> and provides nanotechnology mass measurement of product, test and blanket wafers independent of substrate size or material.

The new metrology tool is equipped with a standard equipment front-end module (EFEM) housing an atmospheric robot within a mini-environment. The wafer handling capabilities of the tool rely on two 300mm front opening unified pods (FOUPs) located side by side at the front of the system. The tool is able to pre-identify the FOUP adaptors to achieve seamless handling. If more measurement capacity is required then an additional measurement station can be mounted on the system.

The DF3 can also be configured to serve as a bridge tool in mixed wafer fab environments where 200 and 300mm wafers are continually interchanged. For use as a bridge tool, one of the tool's

load-ports can be configured for 200mm (either open cassette or SMIF) operation while the other remains at 300mm.

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## *About Metryx*

Metryx is a semiconductor equipment manufacturer specializing in unique nanotechnology mass measurement techniques. Based in Bristol, England, Metryx's non-destructive 200mm and 300mm metrology tools offer atomic layer accuracy making them ideal for material characterization and device manufacture process control. For more information on the company and its products please visit [www.metryx.net](http://www.metryx.net)